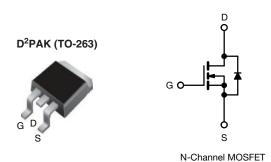
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

E Series Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	700			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.087		
Q _g max. (nC)	62			
Q _{gs} (nC)	16			
Q _{gd} (nC)	15			
Configuration	Single			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- · Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION			
Package	D ² PAK (TO-263)		
Lead (Pb)-free and halogen-free	SiHB100N65E-GE3		

ABSOLUTE MAXIMUM RATINGS	$T_C = 25 ^{\circ}C$, unle	ss otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	650	
Gate-source voltage			V_{GS}	± 30	V
Continuous drain current (T _J = 150 °C)	V at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	30	
	V _{GS} at 10 V	T _C = 100 °C		19	Α
Pulsed drain current ^a			I _{DM}	63	
Linear derating factor				1.47	W/°C
Single pulse avalanche energy b			E _{AS}	127	mJ
Maximum power dissipation			P_{D}	208	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope		dv/dt	100	V/ns	
Reverse diode dv/dt ^c			av/at		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.0 A
- c. $I_{SD} \leq I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	-	0.6	C/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							•
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	650	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.68	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = 250 μA	3.0	-	5.0	V
Osta a sus test as a		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
7		V _{DS} =	650 V, V _{GS} = 0 V	-	-	1	μΑ
Zero gate voltage drain current	I _{DSS}	V _{DS} = 520 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	10	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 12 A	-	0.087	0.100	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 8 V, I _D = 14 A	-	12	-	S
Dynamic							•
Input capacitance	C _{iss}		V _{GS} = 0 V,	-	2137	-	
Output capacitance	C _{oss}	1	$V_{\rm DS} = 100 \text{ V},$	-	89	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	2	-	pF
Effective output capacitance, energy related ^a	$C_{o(er)}$	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	90	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	633	-	
Total gate charge	Qg			-	41	62	
Gate-source charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 14 \text{ A}, V_{DS} = 520 \text{ V}$		-	16	-	nC
Gate-drain charge	Q _{gd}			-	15	-	
Turn-on delay time	t _{d(on)}			-	28	56	
Rise time	t _r	V _{DD} = 520 V, I _D = 14 A,		-	68	136	
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		50	100	ns
Fall time	t _f			-	32	64	
Gate input resistance	R_g	f = 1 MHz, Open Drain		0.5	1.1	2.2	Ω
Drain-Source Body Diode Characteristic	s						•
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	30	
Pulsed diode forward current	I _{SM}			-	-	63	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 14 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 14A, di/dt = 100 A/μs, V _R = 25 V		-	362	724	ns
Reverse recovery charge	Q _{rr}			-	5.0	10	μC
Reverse recovery current	I _{RRM}			_	22	-	A



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

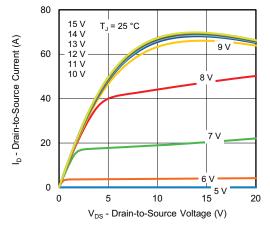


Fig. 1 - Typical Output Characteristics

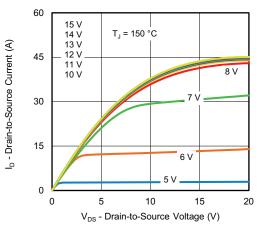


Fig. 2 - Typical Output Characteristics

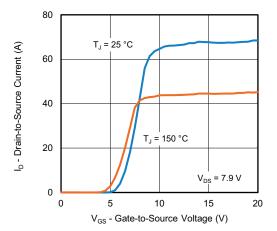


Fig. 3 - Typical Transfer Characteristics

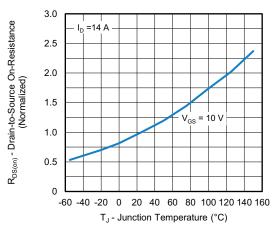


Fig. 4 - Normalized On-Resistance vs. Temperature

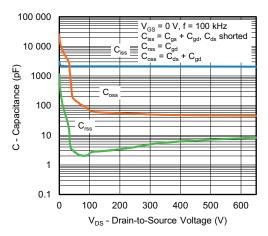


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

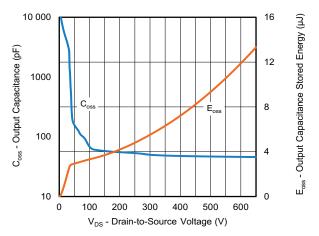


Fig. 6 - Coss and Eoss vs. VDS



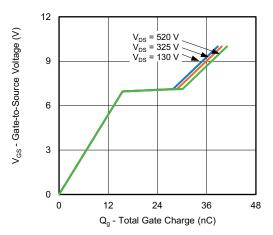


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

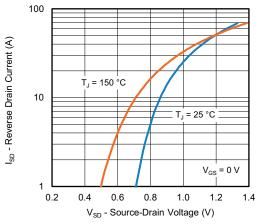


Fig. 8 - Typical Source-Drain Diode Forward Voltage

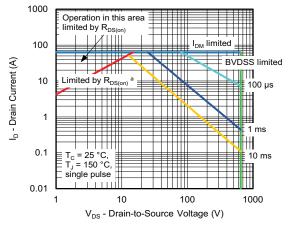


Fig. 9 - Maximum Safe Operating Area



a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

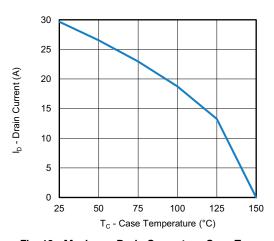


Fig. 10 - Maximum Drain Current vs. Case Temperature

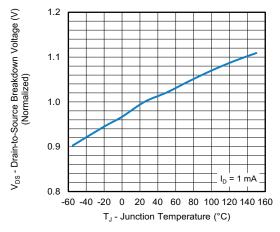


Fig. 11 - Temperature vs. Drain-to-Source Voltage



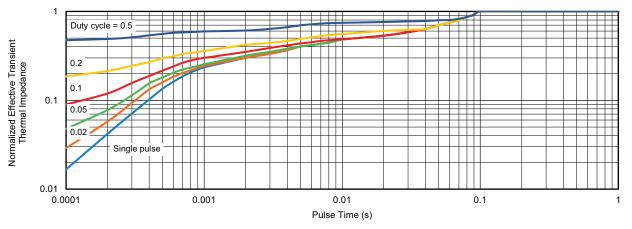


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

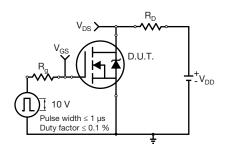


Fig. 13 - Switching Time Test Circuit

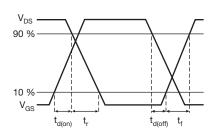


Fig. 14 - Switching Time Waveforms

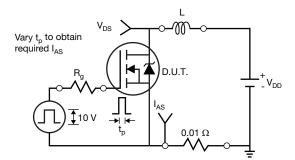


Fig. 15 - Unclamped Inductive Test Circuit

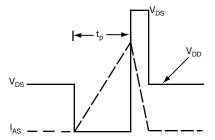


Fig. 16 - Unclamped Inductive Waveforms

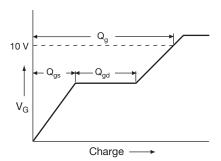


Fig. 17 - Basic Gate Charge Waveform

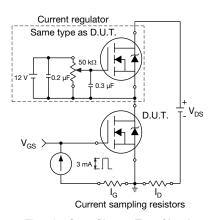
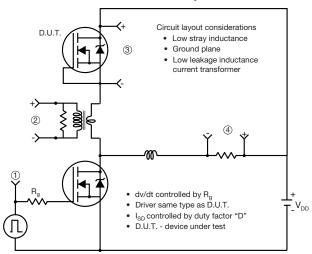


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



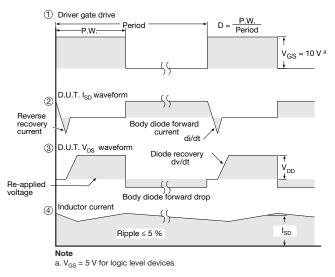


Fig. 19 - For N-Channel

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TO-263AB (HIGH VOLTAGE)







View A - A

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
С	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
Е	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	i
е	2.54 BSC		0.100 BSC	
Н	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	ı	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08

DWG: 5970

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
- 4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
- 5. Dimension b1 and c1 apply to base metal only.
- 6. Datum A and B to be determined at datum plane H.
- 7. Outline conforms to JEDEC outline to TO-263AB.

Document Number: 91364 www.vishay.com Revision: 15-Sep-08





RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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